



BS817

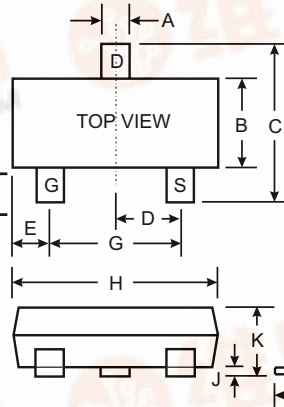
P-CHANNEL ENHANCEMENT MODE DMOS TRANSISTOR

Features

- High Breakdown Voltage
- High Input Impedance
- Fast Switching Speed
- Specially Suited for Telephone Subsets
- Ideal for Automated Surface Mount Assembly

Mechanical Data

- Case: SOT-23, Plastic
- Terminals: Solderable per MIL-STD-202, Method 208
- Terminal Connections (see Diagram)
- Marking: S17
- Weight: 0.008 grams (approx.)



SOT-23		
Dim	Min	Max
A	0.37	0.51
B	1.19	1.40
C	2.10	2.50
D	0.89	1.05
E	0.45	0.61
G	1.78	2.05
H	2.65	3.05
J	0.013	0.15
K	0.89	1.10
L	0.45	0.61
M	0.076	0.178
All Dimensions in mm		

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	$-V_{DS}$	200	V
Drain-Gate Voltage	$-V_{DG}$	200	V
Gate-Source Voltage (pulsed) (Note 2)	V_{GS}	± 20	V
Drain Current (continuous)	$-I_D$	100	mA
Power Dissipation @ $T_C = 50^\circ\text{C}$ (Note 1)	P_d	310	mW
Operating and Storage Temperature Range	T_j, T_{STG}	-55 to +150	$^\circ\text{C}$

Inverse Diode @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Max Forward Current (continuous)	I_F	0.3	A
Forward Voltage Drop (typical) @ $V_{GS} = 0, I_F = 0.3\text{A}, T_j = 25^\circ\text{C}$	V_F	0.85	V

- Notes:
1. Device mounted on Ceramic Substrate 0.7mm x 2.5cm² area.
 2. Pulse Test: Pulse width = 80 μs , duty cycle = 1%.

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Drain-Source Breakdown Voltage	$-V_{(BR)DSS}$	200	230	—	V	$-I_D = 100\mu\text{A}$, $V_{GS} = 0$
Gate-Body Leakage Current	$-I_{GSS}$	—	—	10	nA	$-V_{GS} = 15\text{V}$, $V_{DS} = 0$
Drain-Source Cutoff Current	$-I_{DSS}$ $-I_{DSX}$	—	—	30 1.0	nA μA	$-V_{DS} = 130\text{V}$, $V_{GS} = 0$ $-V_{DS} = 70\text{V}$, $-V_{GS} = 0.2\text{V}$
Gate-Source Threshold Voltage	$-V_{GS(th)}$	—	2.8	3.5	V	$-V_{GS} = V_{DS}$, $-I_D = 1.0\text{mA}$
Drain-Source ON Resistance	$r_{DS(ON)}$	—	30	50	Ω	$-V_{GS} = 2.8\text{V}$, $-I_D = 20\text{mA}$
Thermal Resistance, Junction to Substrate Backside	$R_{\theta JSB}$	—	—	320	K/W	Note 1
Thermal Resistance, Junction to Ambient Air	$R_{\theta JA}$	—	—	400	K/W	Note 1
Input Capacitance Output Capacitance Feedback Capacitance	C_{iss} C_{oss} C_{rss}	—	58 8.0 1.5	—	pF	$-V_{DS} = 20\text{V}$, $V_{GS} = 0$, $f = 1.0\text{MHz}$
Switching Times Turn-On Time Turn-Off Time	t_{ON} t_{OFF}	—	5.0 15	—	ns	$-V_{GS} = 10\text{V}$, $-V_{DS} = 10\text{V}$, $R_D = 100\Omega$

- Notes: 1. Device mounted on ceramic substrate $0.7\text{mm} \times 2.5\text{cm}^2$ area.
2. Pulse test: Pulse width = $80\mu\text{s}$, duty cycle = 1%.

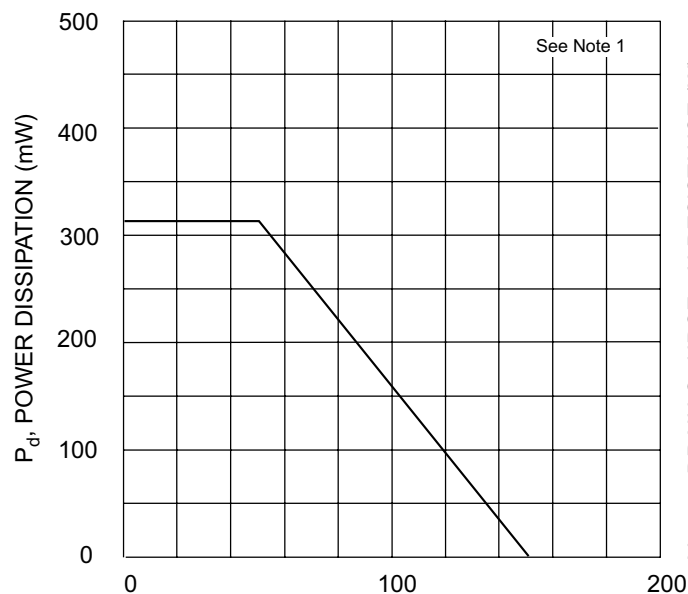


Fig. 1, Power Derating Curve

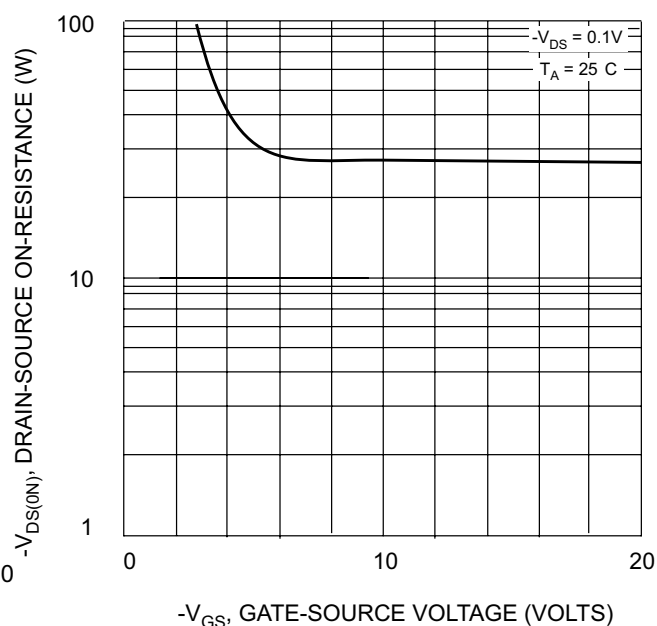


Fig. 2, Drain-Source Resistance vs Gate-Source Voltage